

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-17 (Canceled)

Claim 18 (Previously presented): A method of electrically connecting an electronic device to a substrate, said method comprising:

 passing free ends of a plurality of elongate spring contacts attached to said electronic device into a plurality of rigid, conductive recesses in said substrate, each said recess comprising a bottom portion disposed within said substrate that prevents said free ends from passing through said substrate; and

 applying a force to said electronic device and thereby pressing said free ends against said bottom portions of said rigid, conductive recesses, wherein electrical connections between said elongate spring contacts and said rigid, conductive recesses are established and maintained substantially entirely due to said pressing.

Claim 19 (Previously presented): The method of claim 18, wherein said electronic device comprises a semiconductor device.

Claim 20 (Previously presented): The method of claim 18, wherein each of said recesses is V shaped.

Claim 21 (Previously presented): The method of claim 18, wherein each of said recesses is U shaped.

Claim 22 (Previously presented): The method of claim 18, wherein each of said recesses is trapezoidal shaped.

Claim 23 (Previously presented): The method of claim 18, wherein each of said recesses is wider near a surface of said substrate than within said substrate.

Claim 24 (Previously presented): The method of claim 18, wherein each of said recesses extends into said substrate and is tapered inwardly.

Claim 25 (Previously presented): The method of claim 18 further comprising removing said force, wherein said electrical connections are substantially eliminated.

Claim 26 (Previously presented): A method of electrically connecting an electronic device to a substrate having a surface and a plurality of rigid conductive terminals disposed adjacent said surface, said method comprising:

providing an electronic device having a plurality of elongate, spring contact elements for providing signal inputs to and/or outputs from said electronic device; and

pressing tips of ones of said spring contact elements against ones of said rigid conductive terminals and thereby compressing said spring contact elements and generating in said spring contact elements spring reaction forces that are perpendicular with respect to said surface of said substrate, wherein electrical connections between said elongate spring contacts and said rigid terminals are established and maintained substantially entirely due to said pressing.

Claim 27 (Previously presented): The method of claim 26, wherein:

said terminals comprise recesses in said substrate, and

said step of pressing comprises passing said tips through said recesses.

Claim 28 (Previously presented): The method of claim 27, wherein each said recess comprises a bottom against which one of said tips is pressed.

Claim 29 (Previously presented): The method of claim 28, wherein said bottom prevents said tips from passing through said substrate.

Claim 30 (Previously presented): The method of claim 29, wherein said recesses are cone shaped.

Claim 31 (Previously presented): The method of claim 29, wherein said recesses are concave.

Claim 32 (Previously presented): The method of claim 29, wherein each of said recesses is V shaped.

Claim 33 (Previously presented): The method of claim 29, wherein each of said recesses is U shaped.

Claim 34 (Previously presented): The method of claim 29, wherein each of said recesses is trapezoidal shaped.

Claim 35 (Previously presented): The method of claim 29, wherein each of said recesses is wider near a surface of said substrate than within said substrate.

Claim 36 (Previously presented): The method of claim 29, wherein each of said recesses extends into said substrate and is tapered inwardly.

Claim 37 (Previously presented): The method of claim 26, wherein said electrical connections are substantially eliminated by ceasing said pressing step.

Claim 38 (Previously presented): The method of claim 29, wherein each said recess comprises a cavity in said substrate, wherein said cavity comprises said bottom portion of each said recess.

Claim 39 (Previously presented): The method of claim 29, wherein each said recess comprises:
a cavity in said substrate, and
a metallic plating disposed on a surface of said cavity,
wherein said bottom portion of each said recess comprises said plating.

Claim 40 (Previously presented): The method of claim 29, wherein said substrate comprises a second electronic device to which said electronic device is electrically connected by said electrical connections between said elongate spring contact and said terminals.

Claim 41 (Previously presented): The method of claim 29, wherein said bottom portion of said recess comprises a plated portion of said substrate.

Claim 42 (Previously presented): The method of claim 18, wherein each said recess comprises a cavity in said substrate, wherein said cavity comprises said bottom portion of each said recess.

Claim 43 (Previously presented): The method of claim 18, wherein each said recess comprises:
a cavity in said substrate, and
a metallic plating disposed on a surface of said cavity,
wherein said bottom portion of each said recess comprises said plating.

Claim 44 (Previously presented): The method of claim 18, wherein said substrate comprises a second electronic device to which said electronic device is electrically connected by said electrical connections between said elongate spring contact and said recesses.

Claim 45 (Previously presented): The method of claim 18, wherein said bottom portion of said recess comprises a plated portion of said substrate.

Claim 46 (New): The method of claim 18, wherein:
said elongate spring contacts are electrically conductive;
said recesses are electrically conductive; and
said bottoms of said recesses are electrically conductive.

Claim 47 (New): The method of claim 19, wherein said semiconductor device comprises a semiconductor die comprising an integrated electronic circuit.

Claim 48 (New): The method of claim 29, wherein:
said elongate spring contact elements are electrically conductive;
said recesses are electrically conductive; and
said bottoms of said recesses are electrically conductive.

Claim 49 (New): The method claim 26, wherein said electronic device comprises a semiconductor device.

Claim 50 (New): The method of claim 49, wherein said semiconductor device comprises a semiconductor die comprising an integrated electronic circuit.

Claim 51 (New): The method of claim 26, wherein:
said spring contacts are electrically conductive; and
said terminals are electrically conductive.